

AMENDMENTS TO THE CLAIMS

The following listing of claims will replace all prior versions, and listings, of claims in this application.

1. (Currently Amended) A method Method for conditioning semiconductor wafers and/or hybrids having the steps:

preparing preparation of a space which is at least partially enclosed by a container and has a wafer/hybrid holding device which is located therein and has the purpose of holding a semiconductor wafer and/or hybrid; and

conducting conduction of a dry fluid through the wafer/hybrid holding device in order to heat-treat the wafer/hybrid holding device;

said dry fluid being fed into the container and into said wafer/hybrid holding device via a first line and leaving said wafer/hybrid holding device and container via a second line;

wherein at least a portion of the fluid leaving having left the wafer/hybrid holding device is used to condition the atmosphere within the space by being conducted back into the container via a third line.

2. (Cancelled).

3. (Currently Amended) The method Method according to Claim 1, characterized in that the portion is firstly heat-treated and then allowed to flow out within the space.

4. (Currently amended) The method Method according to Claim 1, characterized in that the portion is heat-treated outside the space and then fed back to the space.

5. (Currently amended) The method Method according to Claim 1, characterized in that the portion is allowed to flow out within the space directly after it leaves the wafer/hybrid holding device.

6. (Currently Amended) The method Method according to Claim 1, characterized in that a first portion of the fluid leaving the sample stage is firstly heat-treated and then allowed to flow out within the space, and a second portion is allowed to flow out within the space directly after it leaves the wafer/hybrid holding device.

7. (Currently Amended) The method Method according to Claim 1, characterized in that at least one of the first and second portions can be regulated as a function of the flow rate.

8. (Currently Amended) The method Method according to Claim 3, characterized in that the portion is heat-treated in that it is used for precooling, ~~in particular for precooling~~ the fluid, outside the space before said portion is allowed to flow out within the space.

9. (Currently Amended) A device Device for conditioning semiconductor wafers and/or hybrids having:

~~an space being at least partially enclosed space by a container and having a wafer/hybrid holding device which is located therein and has the purpose of holding a semiconductor wafer and/or hybrid; and~~

~~a line device for conducting a dry fluid through the wafer/hybrid holding device for heat treating the wafer/hybrid holding device and for conducting at least a portion of the fluid leaving the wafer/hybrid holding device into the space for conditioning the atmosphere in the space.~~

a first line via which the fluid can be conducted into the container and into the wafer/hybrid holding device from outside the space;

a second line via which the fluid can be conducted from the wafer/hybrid holding device to outside the space; and

a third line via which at least a portion of the fluid can be fed back from outside the space into the space for conditioning the atmosphere within the space.

10. (Currently Amended) The device Device according to Claim 9, characterized in that the line device has:

~~a first line via which the fluid can be conducted into the wafer/hybrid holding device from outside the space;~~

~~a second line via which the fluid can be conducted from the wafer/hybrid holding device to outside the space; and~~

~~a third line via which the fluid can be fed back from outside the space into the space;~~

wherein a temperature regulating device is provided between the second and third lines.

11. (Currently Amended) The device Device according to Claim 10, characterized in that outflow elements are provided at the end of the third line.

12. (Currently Amended) The device Device according to Claim 9, characterized in that ~~the line device has:~~

~~a first line via which the fluid can be conducted from outside the space into the wafer/hybrid holding device; and~~
~~further comprising a fourth line via which the fluid can be conducted from the wafer/hybrid holding device into the space.~~

13. (Cancelled)

14. (Currently Amended) The device Device according to Claim 12, characterized in that a valve is provided for regulating the flow rate of the fourth line.

15. (Currently Amended) The device Device according to Claim 10, characterized in that the temperature regulating device has a heating device.

16. (Currently Amended) The device Device according to Claim 10,
characterized in that the temperature regulating device has a heat exchanger to which at
least a portion of the fluid leaving the space can be conducted.

17. (Currently Amended) The device Device according to Claim 16,
characterized in that the heat exchanger is used to precool the fed-in fluid.

18. (Currently Amended) The device Device according to Claim 13 16,
~~characterized in that the line device is designed in such a way that wherein~~ the portion
leaving the heat exchanger can be fed back at least partially into the space in order to
condition the atmosphere.

19. (Currently Amended) The device Device according to Claims 9,
characterized in that a further line is provided via which dry fluid can additionally be
conducted directly into the space from outside the space.

20. (Cancelled).

21. (New) A method for conditioning semiconductor wafers and/or hybrids
having the steps:
preparing a space which is at least partially enclosed and has a wafer/hybrid
holding device which is located therein and has the purpose of holding a semiconductor
wafer and/or hybrid;

conducting a dry fluid into the space and through the wafer/hybrid holding device
in order to heat-treat the wafer/hybrid holding device;
conducting said fluid from the wafer/hybrid holding device to outside the space;
wherein at least a portion of the fluid which has been conducted from the
wafer/hybrid holding device to outside the space is used to condition the atmosphere
within the space by being conducted back into the space.